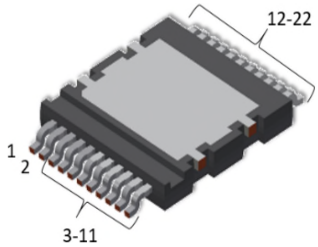
Final datasheet
CoolSiC™ Automotive MOSFET 1200 V in HDSOP-22-3 package



Halogen-free
AEC Qualified
Lead-free
RoHS

Features

- V_{DSS} = 1200 V at T_{vj} = -55...175°C
- I_{DDC} = 18.6 A at T_C = 25°C
- $R_{DS(on)}$ = 160 mΩ at V_{GS} = 20 V, T_{vj} = 25°C
- New performance-optimized chip technology (Gen1p) with improved R_{DSon}* A
- Best in class switching energy for lower switching losses and reduced cooling efforts
- Lowest device capacitances for higher switching speeds and higher power density
- A combination of low C_{rss}/C_{iss} ratio and high $V_{GS(th)}$ to avoid parasitic turn-on and enable unipolar gate driving
- Increased recommended turn-on voltage ($V_{GS(on)}$ = 20 V) for lower $R_{DS(on)}$
- Reduced total gate charge Q_G for lower driving power and losses
- .XT die attach technology for best in class thermal performance
- Low package stray inductance for faster and cleaner switching
- Drive (Kelvin) Source pin for better gate control and reduced switching losses
- Creepage distance > 4.75 mm fitting $V_{rms(max)}$ > 950 V based on IEC60664 for material group I, pollution degree 2
- SMT package for automated assembly and reduced system costs
- Low R_{th} Top-Side Cooled package for best thermal performance and power density

Potential applications

- On-board charger
- DC/DC converter

Product validation

- Qualified for Automotive Applications. Product Validation according to AEC-Q100/101

Description

Pin definition:

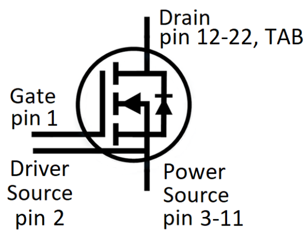
• Pin 1 - Gate

• Pin 2 - Drive Source

• Pin 3...11 - Power Source

• Pin 12...22, TAB - Drain

Note: the drive source and power source pins are not exchangeable, their exchange might lead to malfunction



Type	Package	Marking
AIMCQ120R160M1T	PG-HDSOP-22-3	12A160M1

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1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}				260	°C
MOSFET/body diode thermal resistance, junction-case[1)]	$R_{th(j-c)}$			0.92	1.2	K/W

1) not subject to production test - verified by design/characterization

2 MOSFET

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage[1)]	V_{DSS}	T_{vj} = -55...175 °C		1200	V
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$ [2)]	I_{DDC}	V_{GS} = 20 V	T_c = 25 °C	18.6	A
			T_c = 100 °C	13	
Peak drain current, t_p limited by $T_{vj(max)}$ [2)]	I_{DM}	V_{GS} = 20 V		47	A
Gate-source voltage, max. transient voltage[3)]	V_{GS}	$t_p \leq 0.5$ µs, $D < 0.01$		-10/25	V
Gate-source voltage, max. static voltage[3)]	V_{GS}			-5/23	V
Avalanche energy, single pulse	E_{AS}	I_D = 3.6 A, V_{DD} = 50 V, L = 10 mH		65	mJ
Power dissipation, limited by $T_{vj(max)}$	P_{tot}		T_c = 25 °C	125	W
			T_c = 100 °C	63	

1) tested at Tvj=25°C, verified by design/characterization over full temperature range
2) not subject to production test - verified by design/characterization
3) **Important note:** The selection of positive and negative gate-source voltages impacts the long-term behavior of the device. The design guidelines described in Application Note AN2018-09 must be considered to ensure sound operation of the device over the planned lifetime.

Table 3 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		20	V
Recommended turn-off gate voltage	$V_{GS(off)}$		0	V

Table 4 **Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source on-state resistance	$R_{DS(on)}$	I_D = 5 A	T_{vj} = 25 °C, $V_{GS(on)}$ = 20 V		160	200	mΩ
			T_{vj} = 100 °C, $V_{GS(on)}$ = 20 V		227		
			T_{vj} = 175 °C, $V_{GS(on)}$ = 20 V		327		
			T_{vj} = 25 °C, $V_{GS(on)}$ = 18 V		173		
Gate-source threshold voltage	$V_{GS(th)}$	I_D = 1.5 mA, V_{DS} = V_{GS} (tested after 1 ms pulse at V_{GS} = 20 V)	T_{vj} = 25 °C	3.7	4.4	5.1	V
			T_{vj} = 175 °C		3.6		
Zero gate-voltage drain current	I_{DSS}	V_{DS} = 1200 V, V_{GS} = 0 V	T_{vj} = 25 °C		0.1	4.5	µA
			T_{vj} = 175 °C		10		
Gate leakage current	I_{GSS}	V_{DS} = 0 V	V_{GS} = 25 V			100	nA
			V_{GS} = -10 V			-100	
Forward transconductance	g_{fs}	I_D = 5 A, V_{DS} = 20 V			3.1		S
Short-circuit withstand time[1)]	t_{SC}	V_{DD} ≤ 800 V, $V_{DS,peak}$ < 1200 V, $T_{vj(start)}$ = 25 °C, $R_{G,ext}$ = 5 Ω	$V_{GS(on)}$ = 20 V		1.5		µs
			$V_{GS(on)}$ = 18 V		2		
			$V_{GS(on)}$ = 15 V		2.5		
Internal gate resistance	$R_{G,int}$	f = 1 MHz, V_{AC} = 25 mV			4.8		Ω
Input capacitance	C_{iss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			350		pF
Output capacitance	C_{oss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			20		pF
Reverse transfer capacitance	C_{rss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			1		pF
C_{oss} stored energy	E_{oss}	V_{DD} = 800 V, V_{GS} = 0 V, f = 100 kHz, V_{AC} = 25 mV			8.1		µJ
Total gate charge	Q_G	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, turn-on pulse			14		nC
Plateau gate charge	$Q_{GS(pl)}$	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, turn-on pulse			4		nC
Gate-to-drain charge	Q_{GD}	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, turn-on pulse			2		nC
Turn-on delay time	$t_{d(on)}$	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, $L_σ$ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		6		ns
			T_{vj} = 175 °C		5.8		

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Rise time	t_r	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, L_σ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		3.5		ns
			T_{vj} = 175 °C		4		
Turn-off delay time	$t_{d(off)}$	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, L_σ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		9.5		ns
			T_{vj} = 175 °C		10.3		
Fall time	t_f	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, L_σ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		20.4		ns
			T_{vj} = 175 °C		22.1		
Turn-on energy	E_{on}	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, L_σ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		44.3		µJ
			T_{vj} = 175 °C		53		
Turn-off energy	E_{off}	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, L_σ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		22		µJ
			T_{vj} = 175 °C		25		
Total switching energy	E_{tot}	V_{DD} = 800 V, I_D = 5 A, V_{GS} = 0/20 V, $R_{G,ext}$ = 5 Ω, L_σ = 13 nH, diode: body diode at V_{GS} = 0 V	T_{vj} = 25 °C		66.3		µJ
			T_{vj} = 175 °C		78		
Virtual junction temperature	T_{vj}			-55		175	°C

1) not subject to production test - verified by design/characterization

***Note**: Characteristics at T_{vj} = 25°C, unless otherwise specified.*

3 Body diode (MOSFET)

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage[1)]	V_{DSS}	T_{vj} = -55...175 °C		1200	V
Continuous reverse drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$ [2)]	I_{SDC}	V_{GS} = 0 V	T_c = 25 °C	10.8	A
			T_c = 100 °C	10.8	
Peak reverse drain current, t_p limited by $T_{vj(max)}$ [2)]	I_{SM}	V_{GS} = 0 V		10.8	A

1) tested at Tvj=25°C, verified by design/characterization over full temperature range

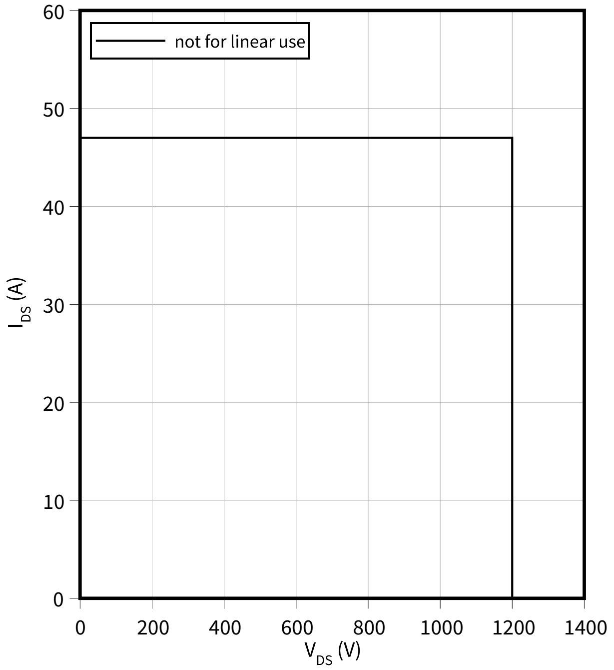
2) not subject to production test - verified by design/characterization

Table 6 **Characteristic values**

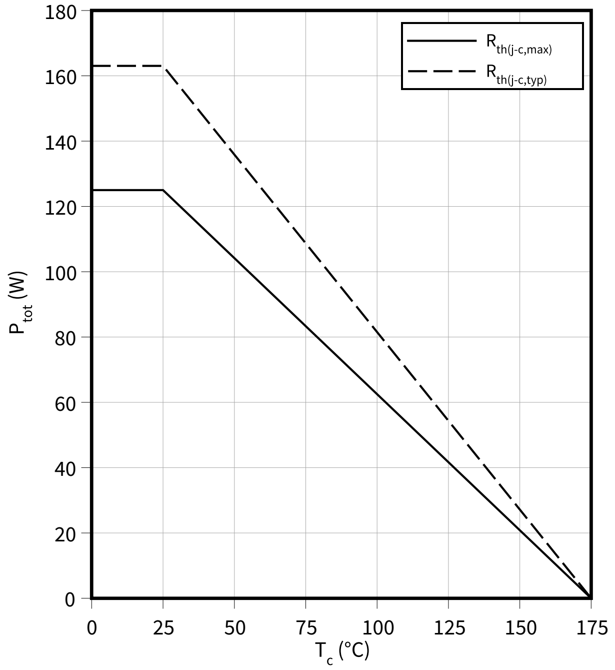
Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	I_{SD} = 5 A, V_{GS} = 0 V	T_{vj} = 25 °C		3.9	5	V
			T_{vj} = 100 °C		3.8		
			T_{vj} = 175 °C		3.7		
MOSFET forward recovery charge	Q_{fr}	V_{DD} = 800 V, I_{SD} = 5 A, V_{GS} = 0 V, $-di_{SD}/dt$ = 1000 A/µs, Q_{fr} includes also Q_C	T_{vj} = 25 °C		101		nC
			T_{vj} = 175 °C		122		
MOSFET peak forward recovery current	I_{frm}	V_{DD} = 800 V, I_{SD} = 5 A, V_{GS} = 0 V, $-di_{SD}/dt$ = 1000 A/µs, Q_{fr} includes also Q_C	T_{vj} = 25 °C		6.6		A
			T_{vj} = 175 °C		9		
Virtual junction temperature	T_{vj}			-55		175	°C

4 Characteristics diagrams

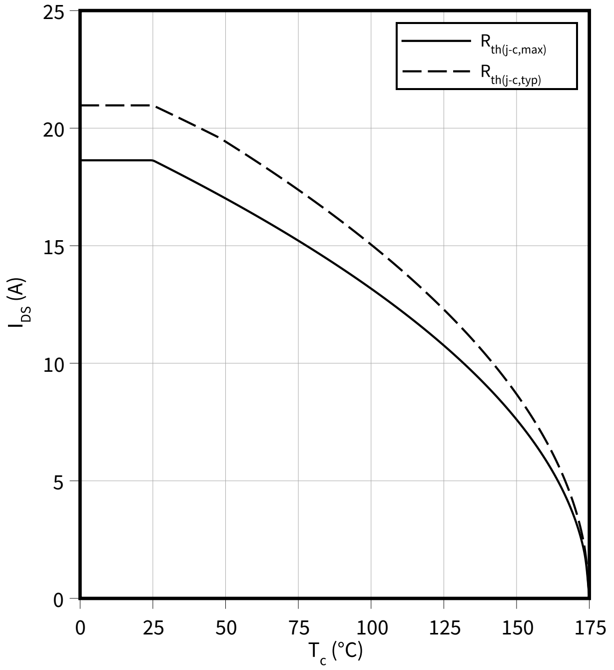
Reverse bias safe operating area (RBSOA)
$I_{DS} = f(V_{DS})$
$T_{vj} \leq 175$ °C, $V_{GS} = 0/20$ V, $T_c = 25$ °C



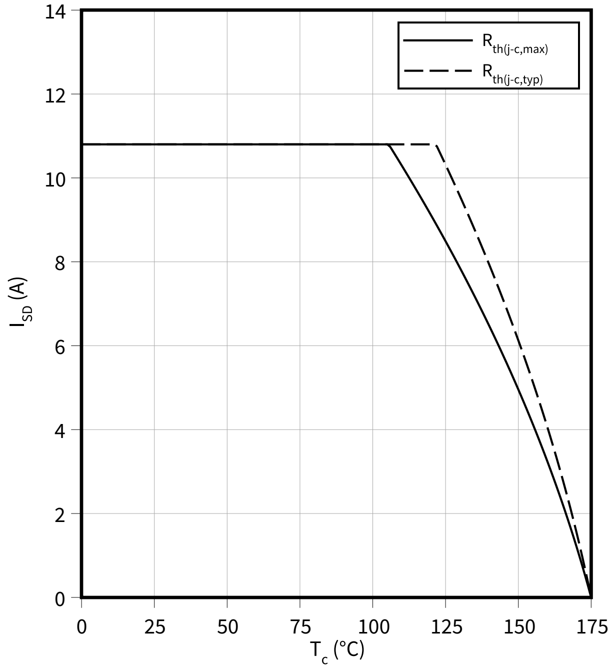
Power dissipation as a function of case temperature
$P_{tot} = f(T_c)$
$T_{vj} \leq 175$ °C



Maximum DC drain to source current as a function of case temperature limited by bond wire
$I_{DS} = f(T_c)$



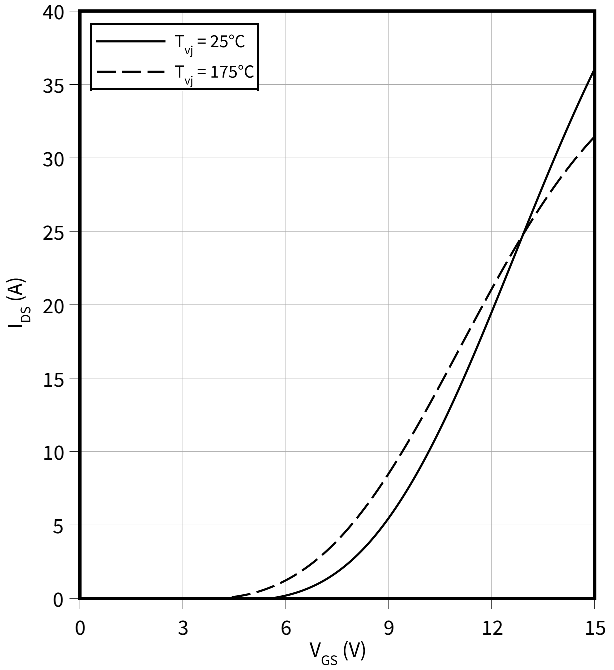
Maximum source to drain current as a function of case temperature
$I_{SD} = f(T_c)$
$V_{GS} = 0$ V



Typical transfer characteristic

$I_{DS} = f(V_{GS})$

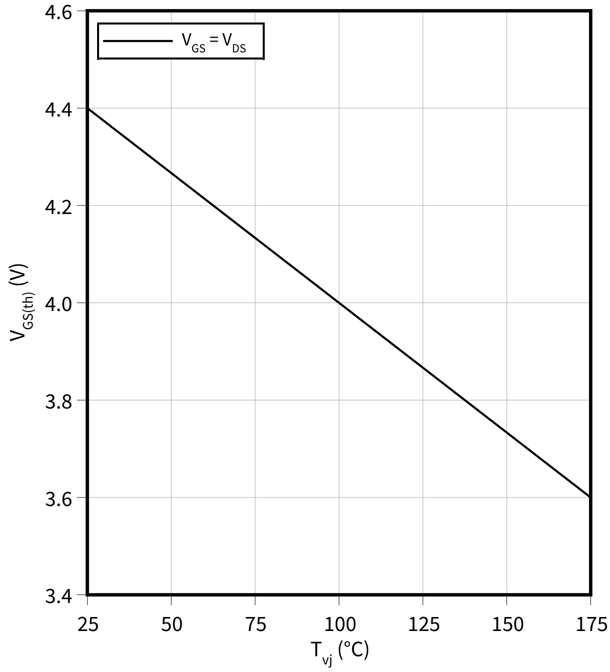
$V_{DS} = 20$ V, $t_p = 20$ µs



Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$

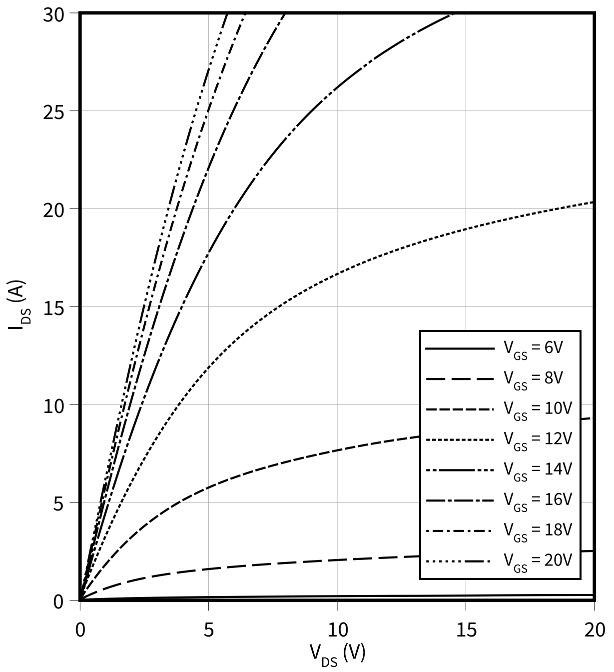
$I_D = 1.5$ mA



Typical output characteristic, V_{GS} as parameter

$I_{DS} = f(V_{DS})$

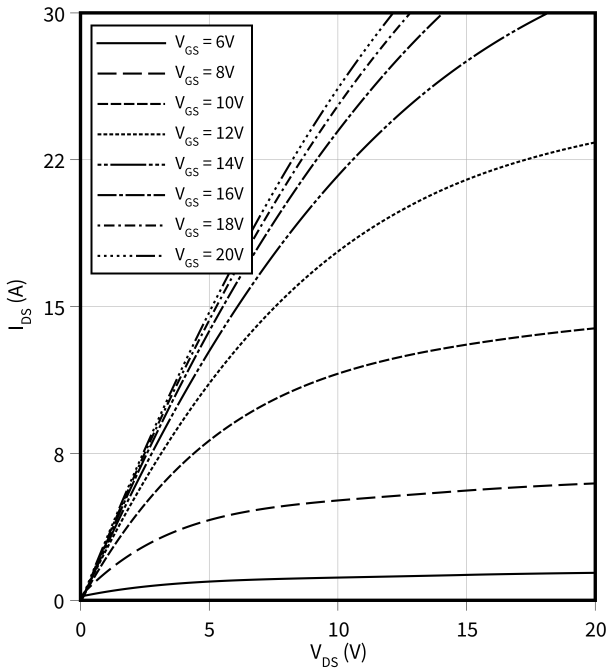
$T_{vj} = 25$ °C, $t_p = 20$ µs



Typical output characteristic, V_{GS} as parameter

$I_{DS} = f(V_{DS})$

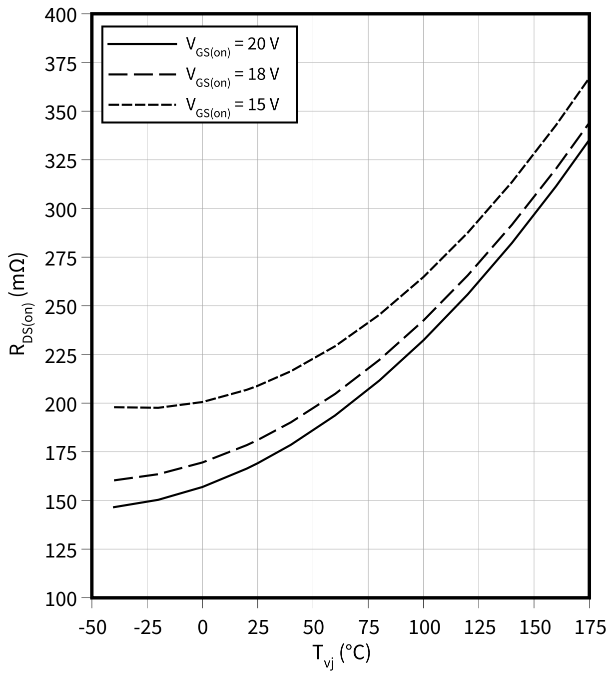
$T_{vj} = 175$ °C, $t_p = 20$ µs



Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$

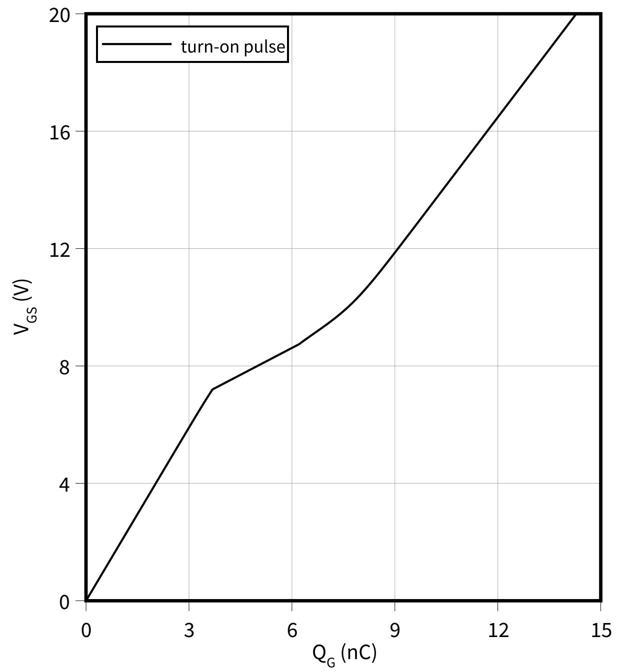
$I_D = 5\ A$



Typical gate charge

$V_{GS} = f(Q_G)$

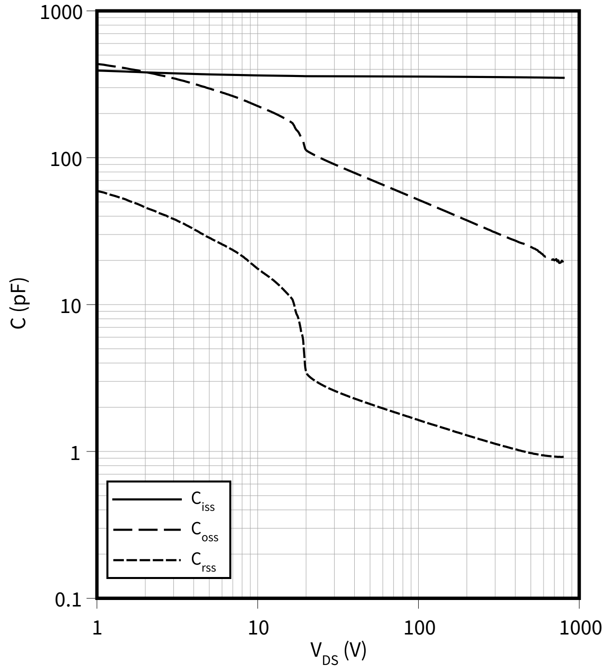
$I_D = 5\ A, V_{DS} = 800\ V$



Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$

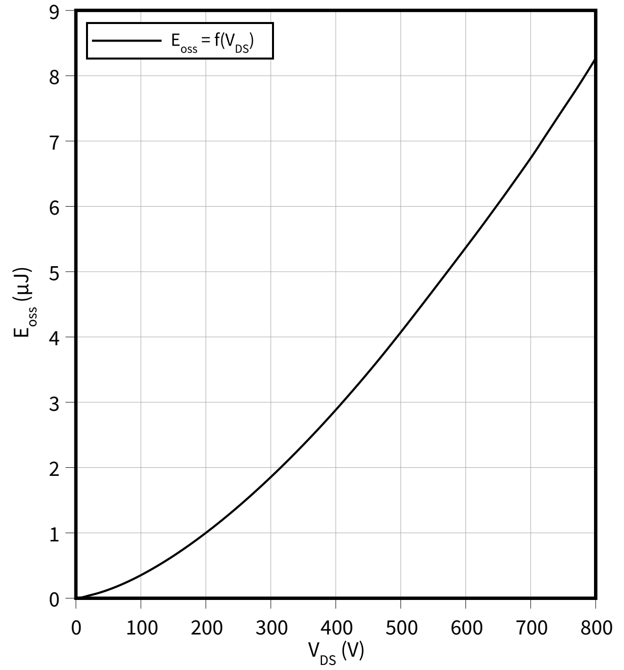
$f = 100\ kHz, V_{GS} = 0\ V$



Typical C_{oss} stored energy

$E_{oss} = f(V_{DS})$

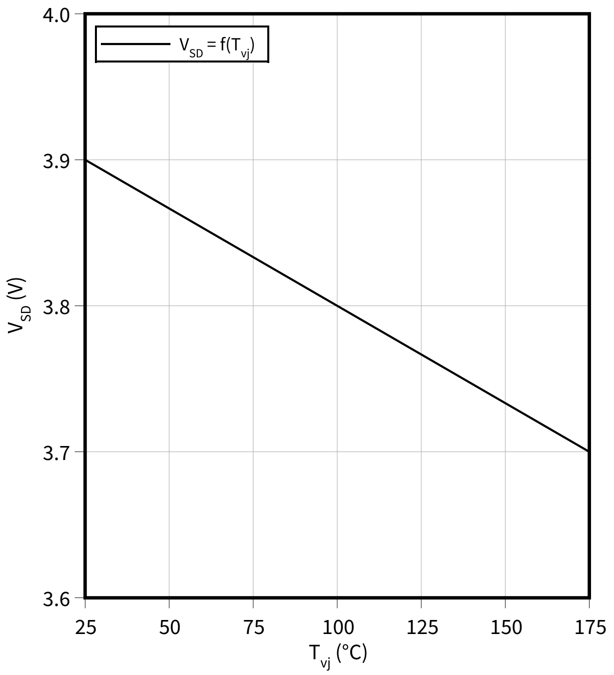
$f = 100\ kHz, V_{GS} = 0\ V$



Typical reverse drain voltage as function of junction temperature

$V_{SD} = f(T_{vj})$

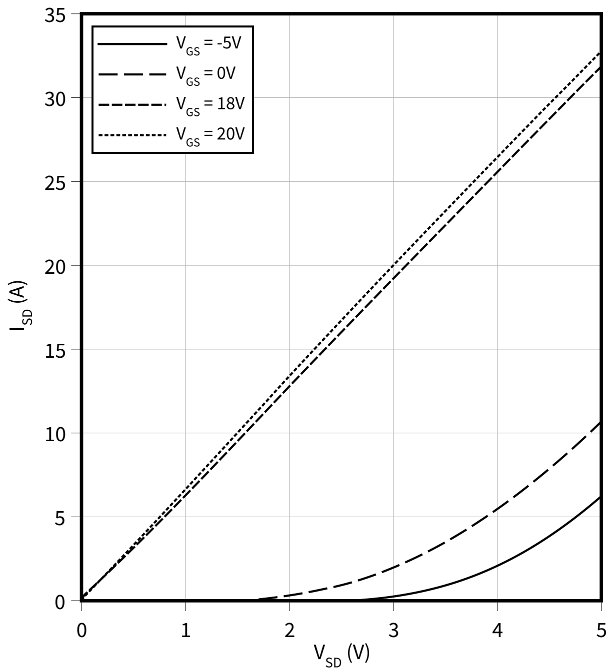
$I_{SD} = 5$ A, $V_{GS} = 0$ V



Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$

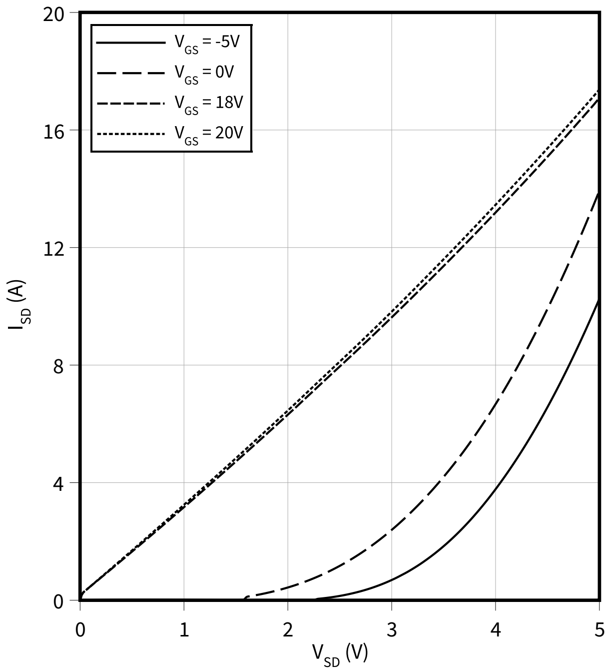
$T_{vj} = 25$ °C, $t_p = 20$ µs



Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$

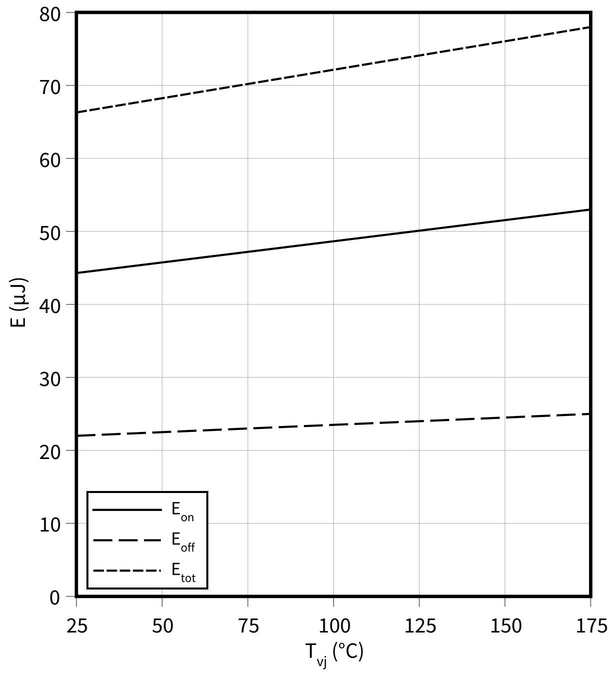
$T_{vj} = 175$ °C, $t_p = 20$ µs



Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$E = f(T_{vj})$

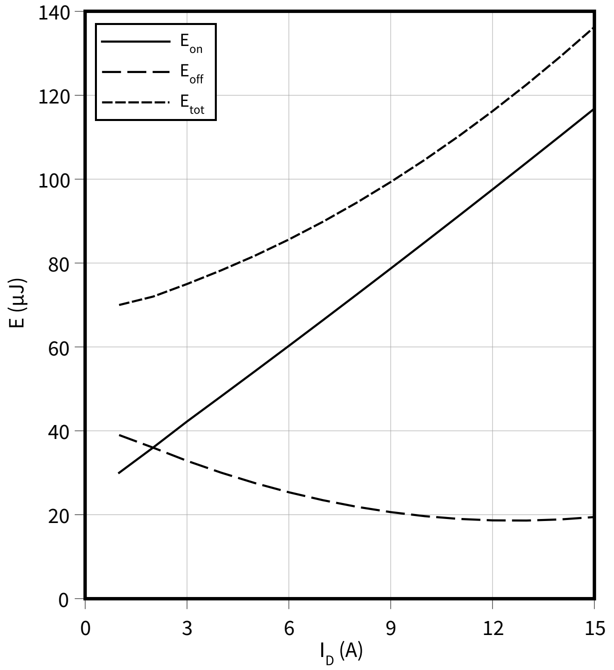
$V_{GS} = 0/20$ V, $I_D = 5$ A, $R_{G,ext} = 5\ \Omega$, $V_{DD} = 800$ V



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$E = f(I_D)$

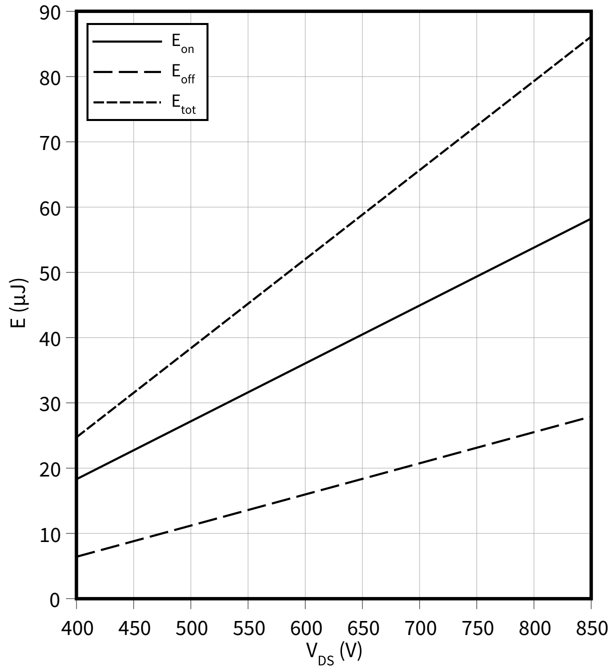
V_{GS} = 0/20 V, T_{vj} = 175 °C, $R_{G,ext}$ = 5 Ω, V_{DD} = 800 V



Typical switching energy as a function of drain voltage, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$E = f(V_{DS})$

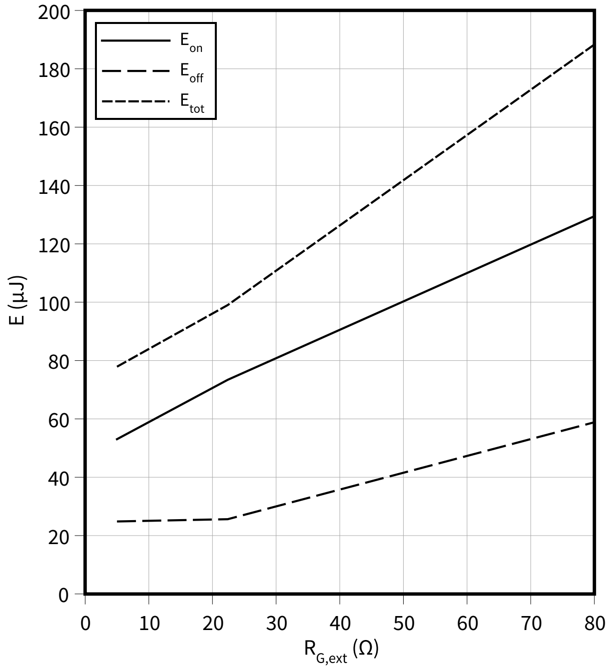
V_{GS} = 0/20 V, I_D = 5 A, T_{vj} = 175 °C, $R_{G,ext}$ = 5 Ω



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: V_{GS} = 0 V

$E = f(R_{G,ext})$

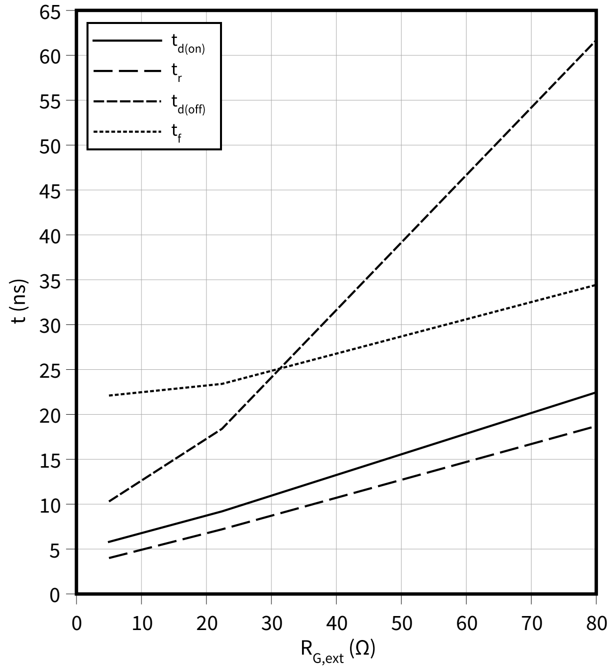
V_{GS} = 0/20 V, I_D = 5 A, T_{vj} = 175 °C, V_{DD} = 800 V



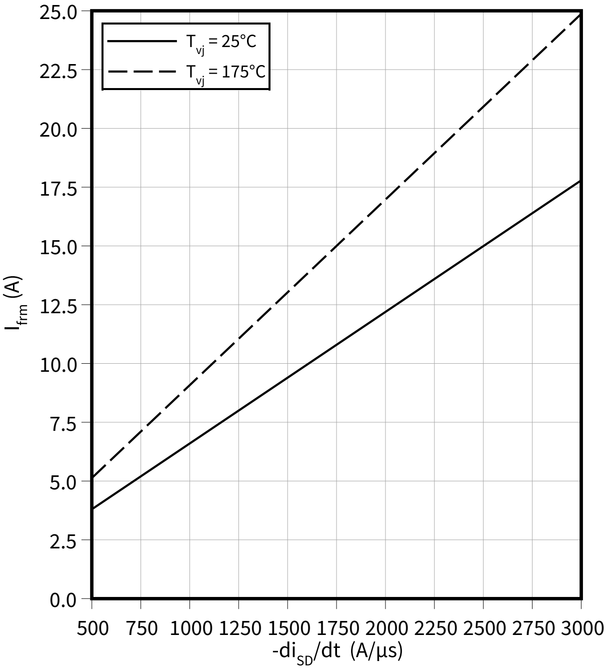
Typical switching times as a function of gate resistance

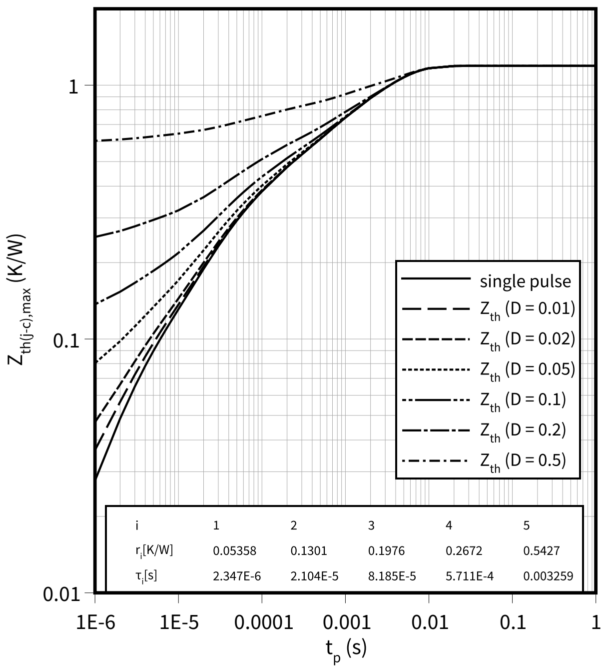
$t = f(R_{G,ext})$

V_{GS} = 0/20 V, I_D = 5 A, T_{vj} = 175 °C, V_{DD} = 800 V



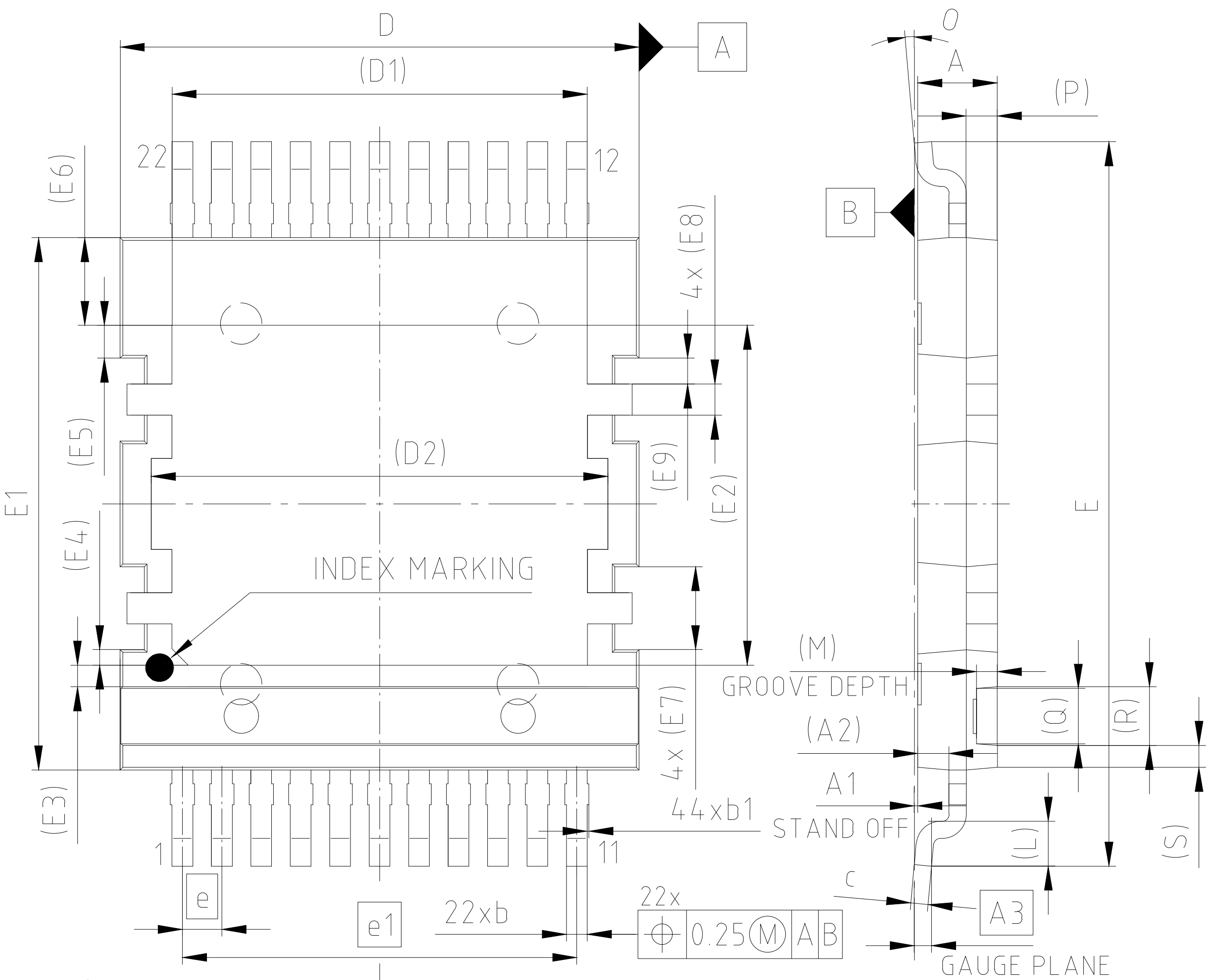
Typical MOSFET peak forward recovery current as a function of reverse drain current slope	**Max. transient thermal impedance (MOSFET/diode)**
$I_{frm} = f(-di_{SD}/dt)$ $V_{GS} = 0/20$ V, $I_{SD} = 5$ A, $V_{DD} = 800$ V	$Z_{th(j-c),max} = f(t_p)$ $D = t_p/T$

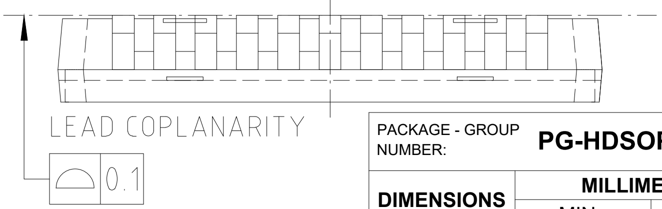




i	1	2	3	4	5
r_i[K/W]	0.05358	0.1301	0.1976	0.2672	0.5427
τ_i[s]	2.347E-6	2.104E-5	8.185E-5	5.711E-4	0.003259

5 Package outlines





NOTES:

ALL METAL SURFACES TIN PLATED EXCEPT AREA OF CUT

DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS

PACKAGE - GROUP NUMBER:	PG-HDSOP-22-U03	
DIMENSIONS	**MILLIMETERS**	
	MIN.	MAX.
A	2.25	2.35
A1	0.00	0.15
A2	0.90	
A3	0.50	
b	0.50	0.70
b1	---	0.15
c	0.46	0.58
D	14.90	15.10
D1	12.00	
D2	13.20	
E	20.81	21.11
E1	15.30	15.50
E2	9.83	

DIMENSIONS	**MILLIMETERS**	
	MIN.	MAX.
E3	0.625	
E4	0.45	
E5	0.95	
E6	2.53	
E7	2.40	
E8	0.90	
E9	0.75	
e	1.14	
e1	11.4	
L	1.30	
M	0.60	
N	22	
O	0°	8°
P	0.90	
Q	1.60	
R	1.70	
S	0.631	

Figure 1

6 Testing conditions

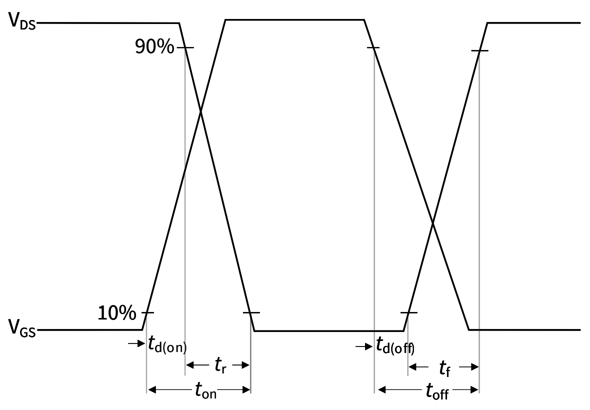


Figure A. **Definition of switching times**

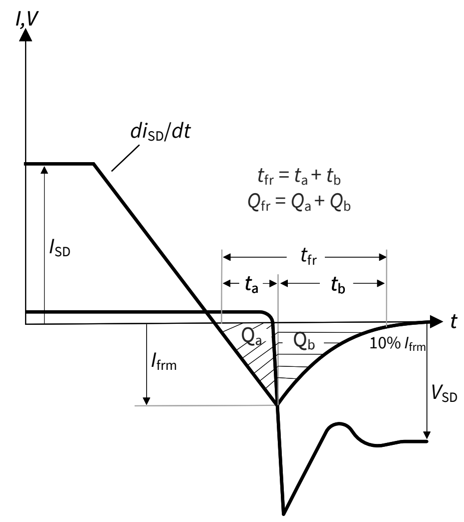


Figure B. **Definition of body diode switching characteristics**

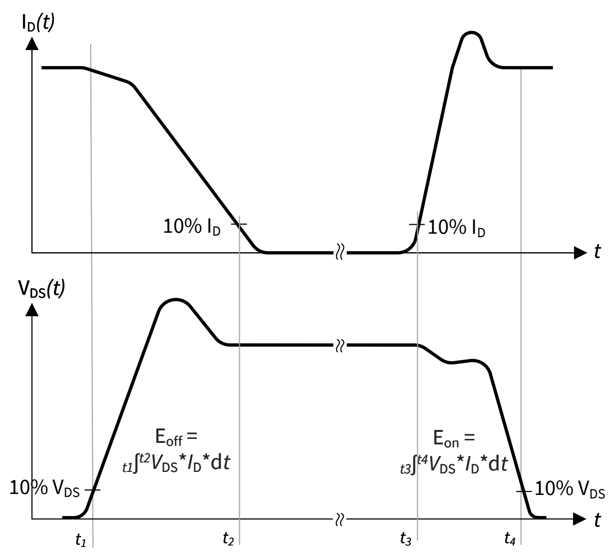


Figure C. **Definition of switching losses**

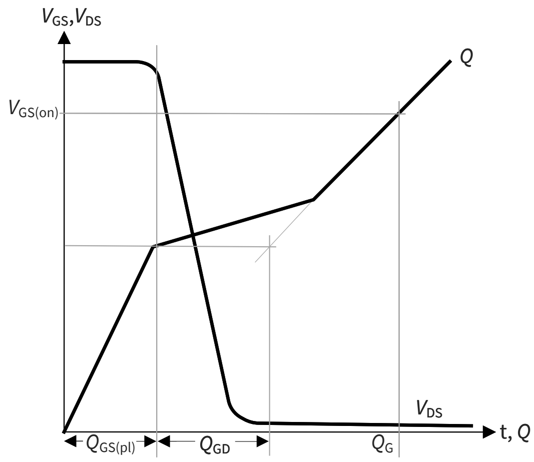


Figure D. **Definition of QGD**

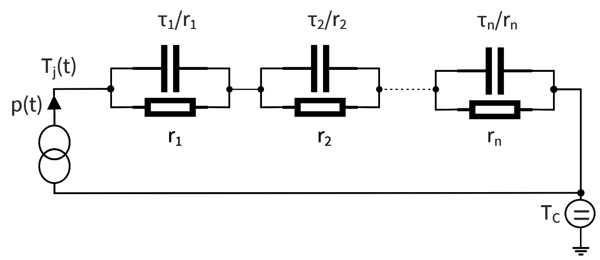


Figure E. **Thermal equivalent circuit**

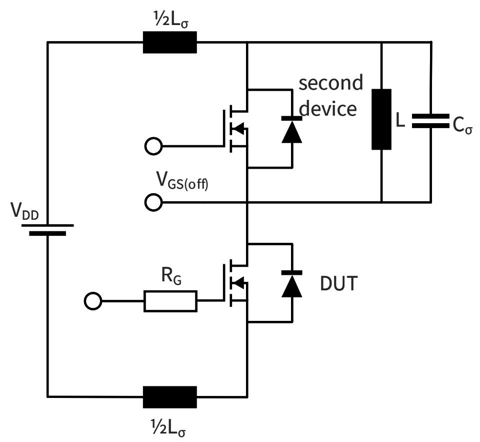


Figure F. **Dynamic test circuit**
Parasitic inductance L_σ,
Parasitic capacitor C_σ,

Figure 2

Revision history

Document revision	Date of release	Description of changes
0.10	2023-01-17	Target datasheet
0.20	2024-07-01	Preliminary datasheet
1.00	2024-07-22	Final datasheet

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